

ABSTRACT OF THE DISCLOSURE

A lead frame for a semiconductor chip package includes a frame body and at least two chip-receiving windows formed in the frame body. Each chip-receiving window receives a respective integrated circuit chip therein. A plurality of internal connection leads are formed on the frame body adjacent to the chip-receiving windows, and are connected electrically to bonding pads on the integrated circuit chips in the chip-receiving windows such that internal electrical connection among the integrated circuit chips can be established via the internal connection leads. A plurality of external connection leads are formed on the frame body adjacent to at least one of the chip-receiving windows, and are connected electrically to the bonding pads on the integrated circuit chip in the adjacent chip-receiving window. The external connection leads serve as terminal pins such that external electrical connection with the integrated circuit chip in the adjacent chip-receiving window can be established via the external connection leads.